

# *In situ* TEM Studies of Ion Beam Radiation Effects

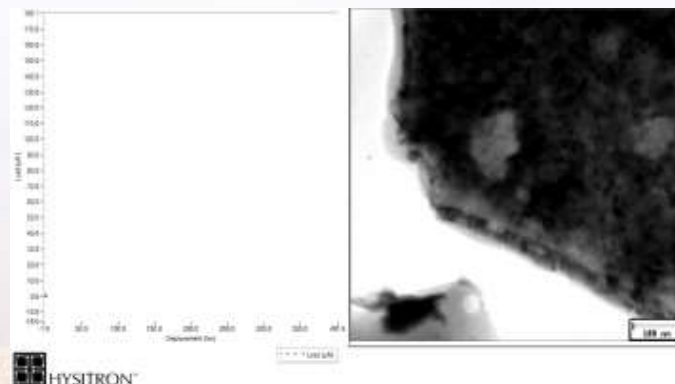
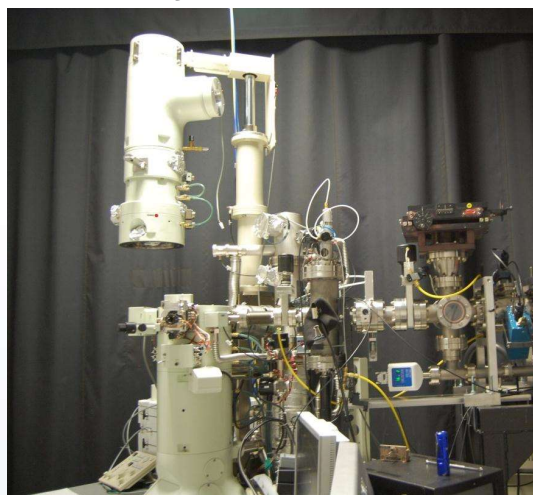
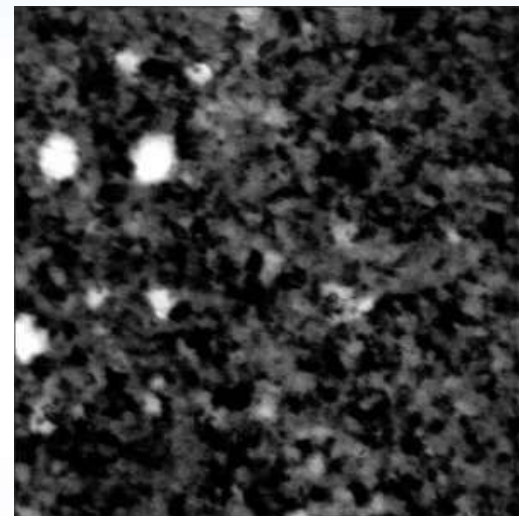
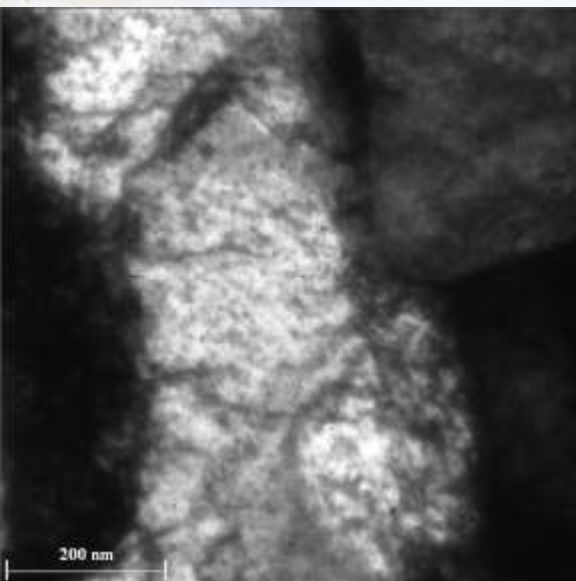
SAND2013-3496C

K. Hattar

Ion Beam Lab

Sandia National Laboratories

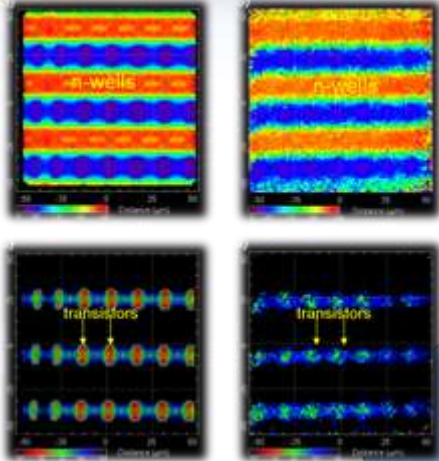
May 14, 2013



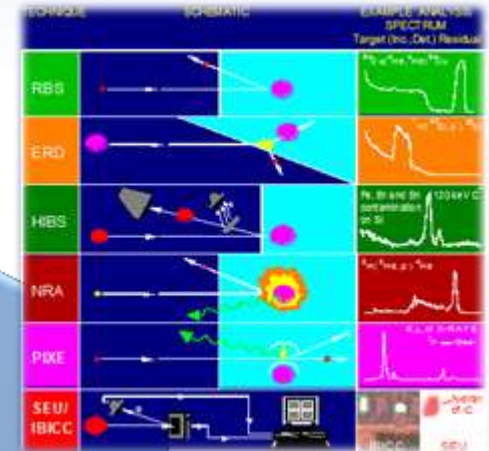
*In situ* Ion Irradiation TEM  
is operational,  
but still in development



# Sandia's Ion Beam Laboratory



Ion Beam Analysis (IBA)

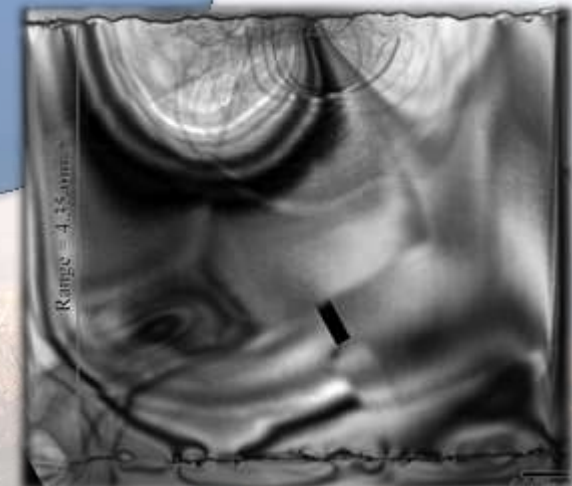


Radiation Effects  
Microscopy (REM)



Ion Beam  
Modification  
(IBM)

*In situ* Ion Irradiation Transmission  
Electron Microscopy  
( $I^3$ TEM)

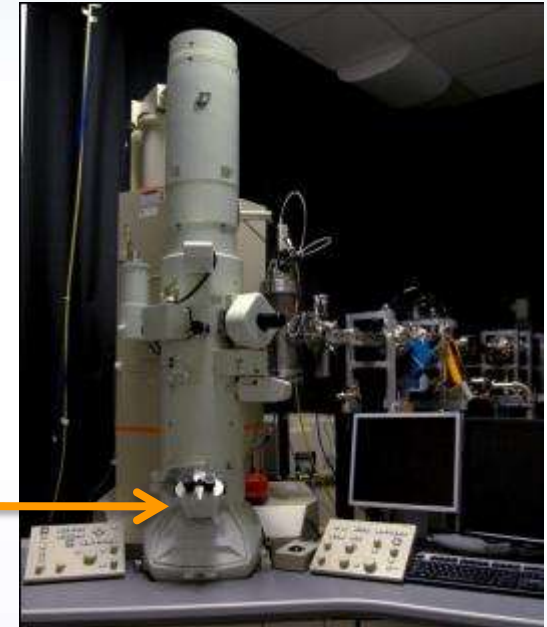
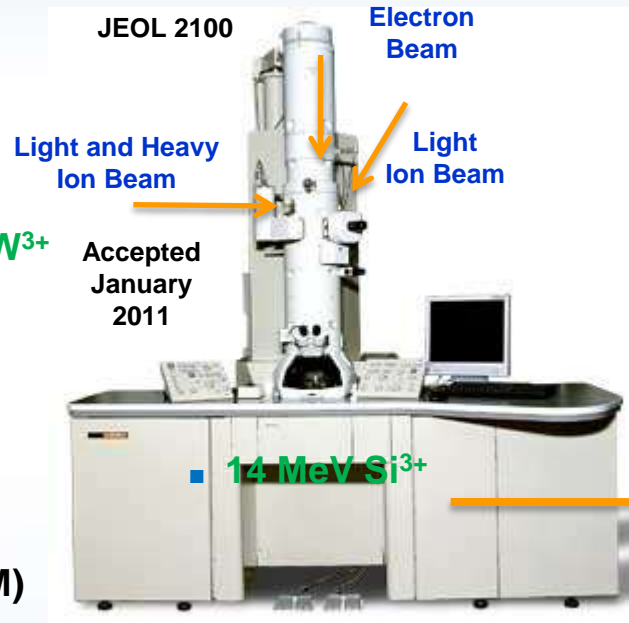


# *In situ* Ion Irradiation TEM (I<sup>3</sup>TEM)

Collaborators: D. Buller, B.G. Clark, & B.L. Doyle

## Proposed Capabilities

- 200 kV LaB<sub>6</sub> TEM
- Ion beams considered:
  - 1 MeV H<sup>1+</sup>
  - 3 MeV He<sup>1+</sup> Si<sup>3+</sup> Ni<sup>3+</sup> Cu<sup>3+</sup> Au<sup>3+</sup>W<sup>3+</sup>
  - 14 MeV Si<sup>3+</sup>
  - 10 keV D<sup>2+</sup>
  - 8 to 10 keV He<sup>+</sup>
- All beams hit the same location
- Electron tomography
- Nanosecond time resolution (DTEM)
- Precession scanning (EBSD in TEM)
- *In situ* PL, CL, and IBIL
- *In situ* heating and cooling stages
- *In situ* electrical measurement stage
- *In situ* quantitative mechanical testing
- *In situ* vapor phase stage
- *In situ* liquid mixing stage



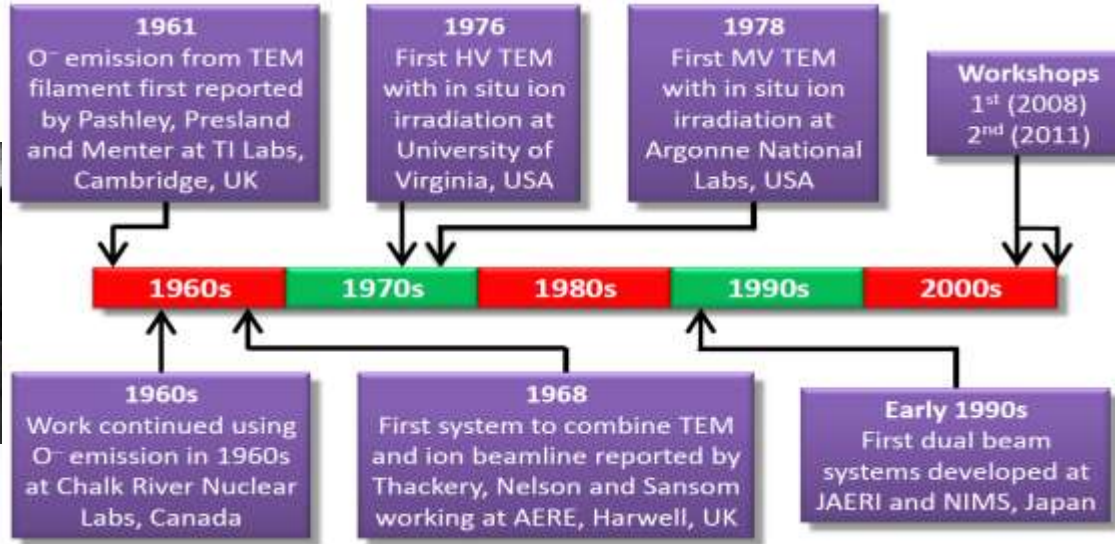
We have completed the Tandem accelerator connection and Colutron accelerator connection.

Many potential additions are being considered



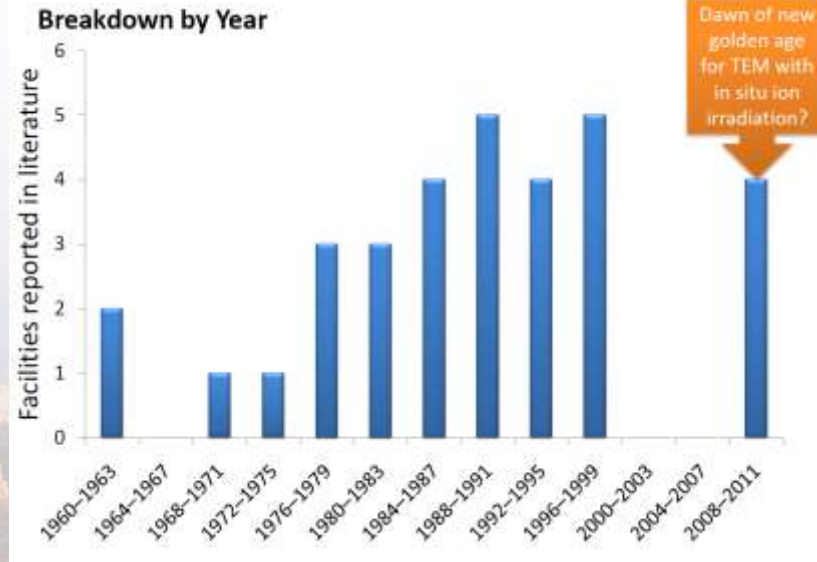
# History of *in situ* Irradiation TEM

Courtesy of: J. Hinks



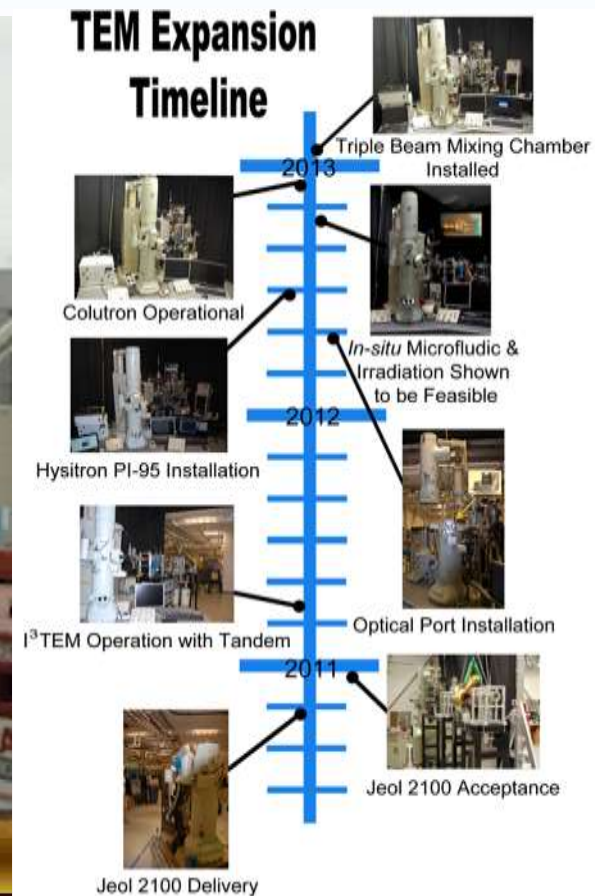
*“The direct observation of ion damage in the electron microscope thus represents a powerful means of studying radiation damage”*

D.W. Pashley and A.E.B Presland *Philosophical Magazine* **6 (68)** (1961) p1002

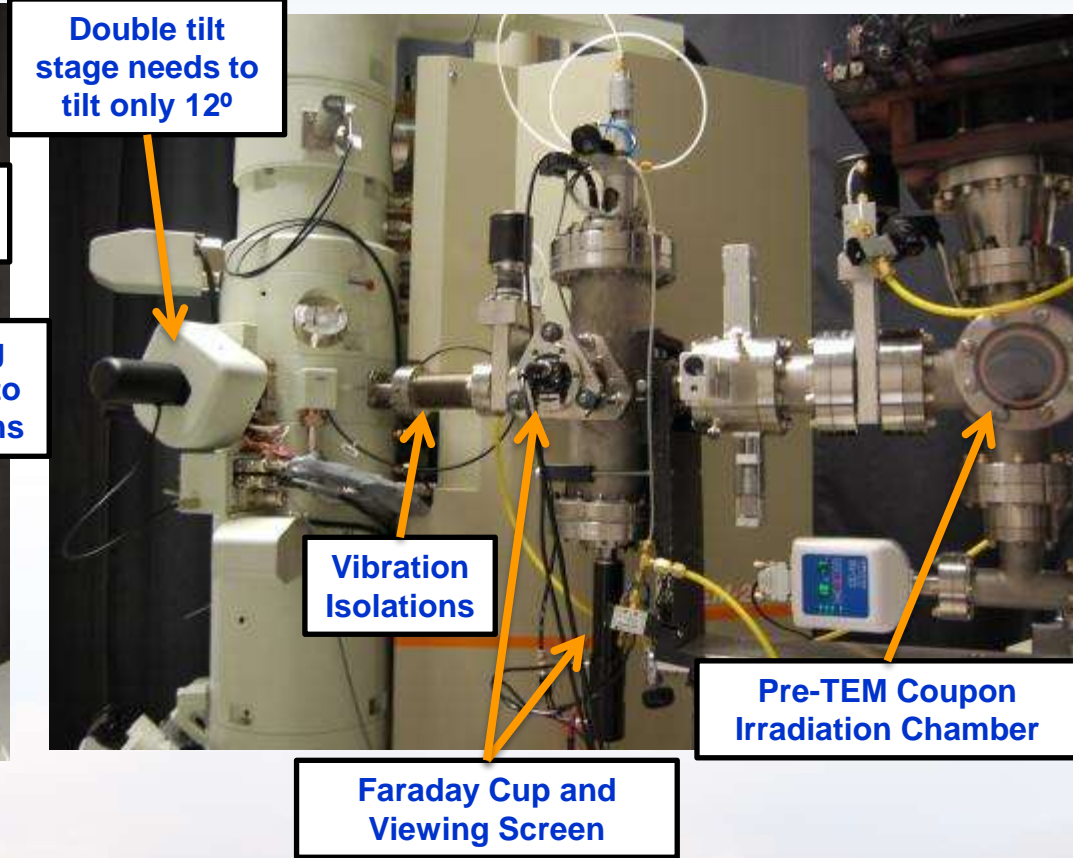
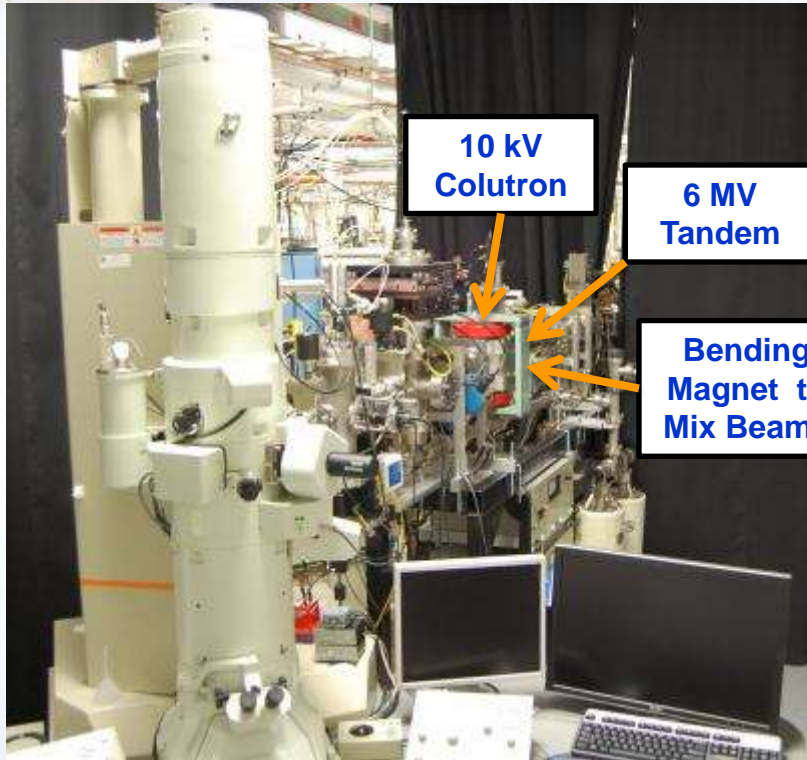




# I<sup>3</sup>TEM History at the Ion Beam Lab



# Current Status of the *In situ* TEM Beamline



Beam burn from 14 MeV Si

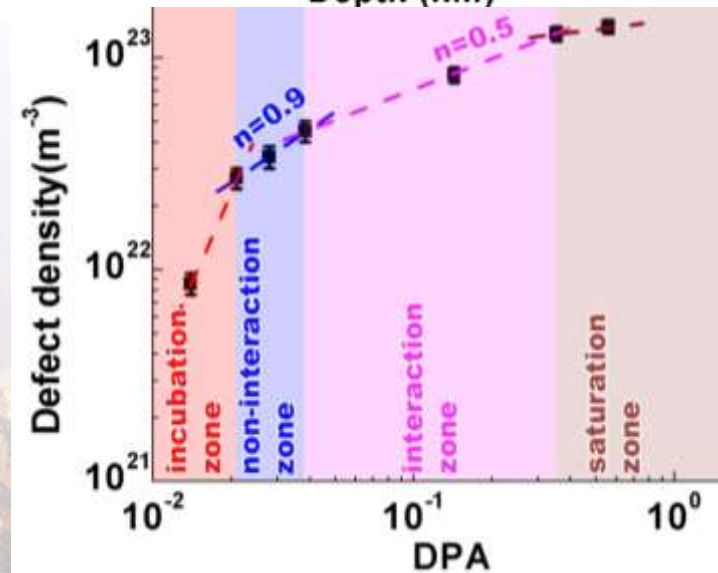
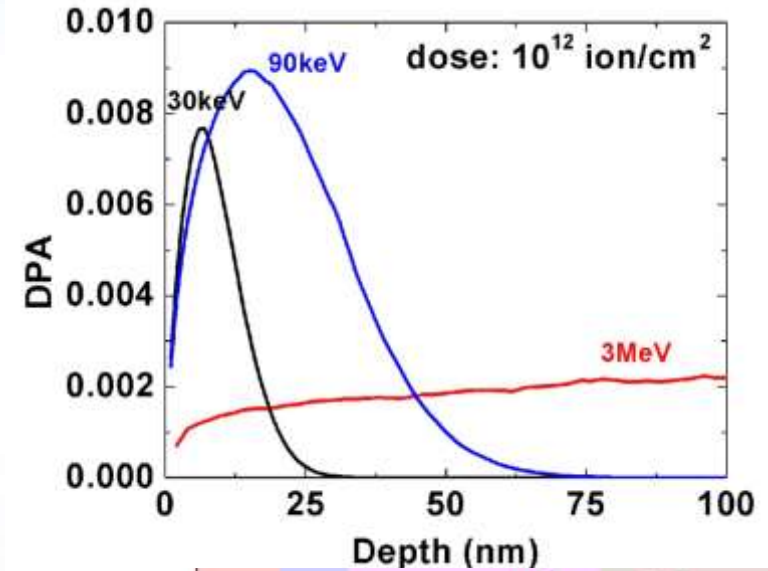
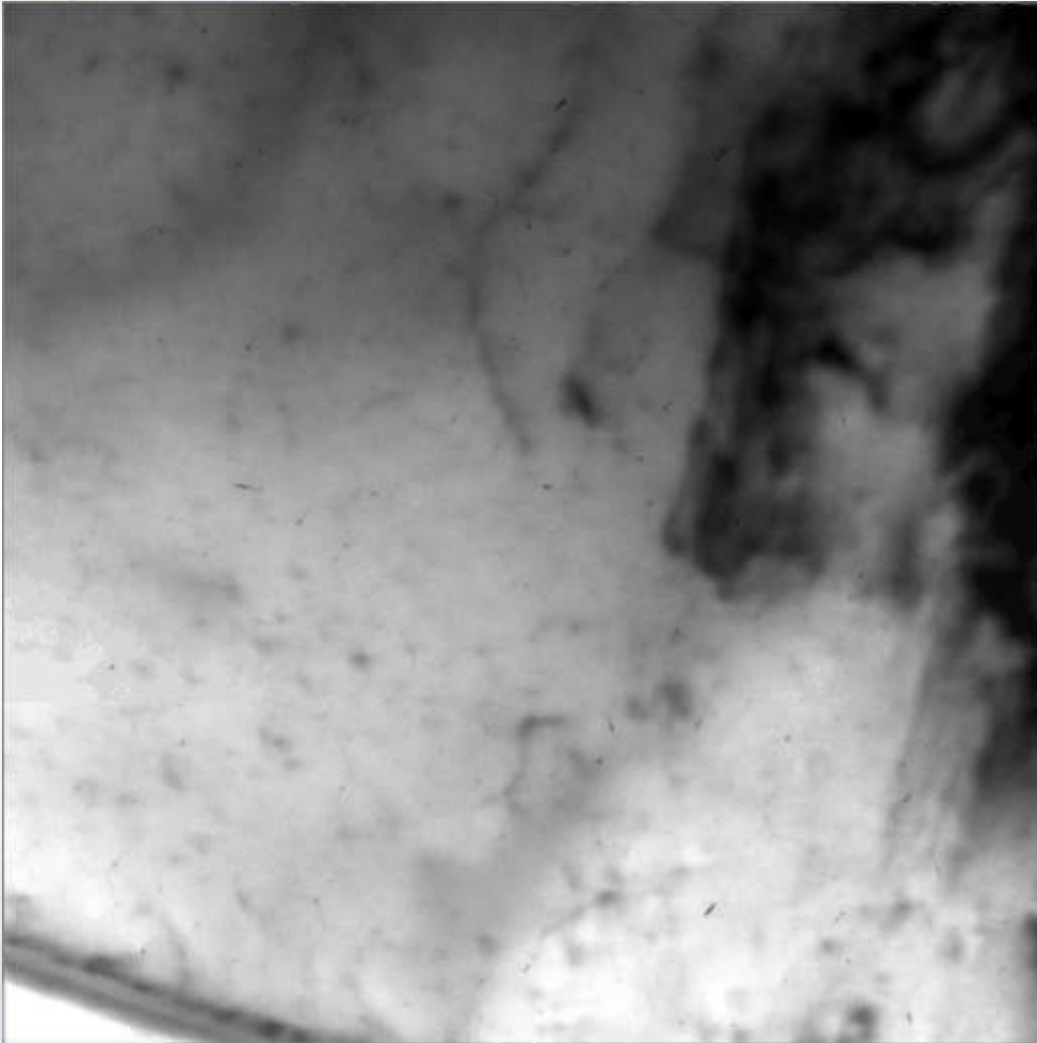
**$I^3$ TEM is operational, but also still in development**

**Microfluidic Holder Beam Burn**



# Evolution of Radiation Defects in Cu TEM Foil

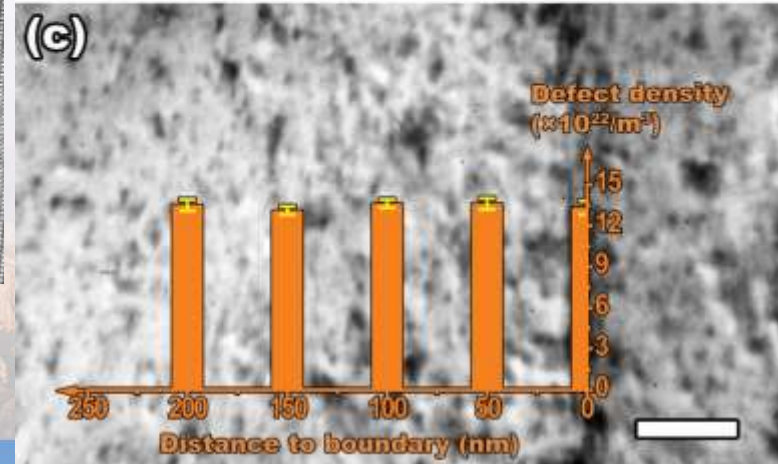
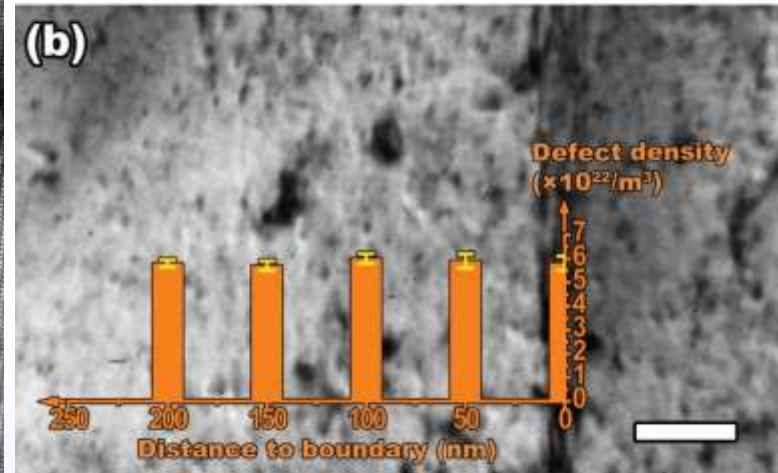
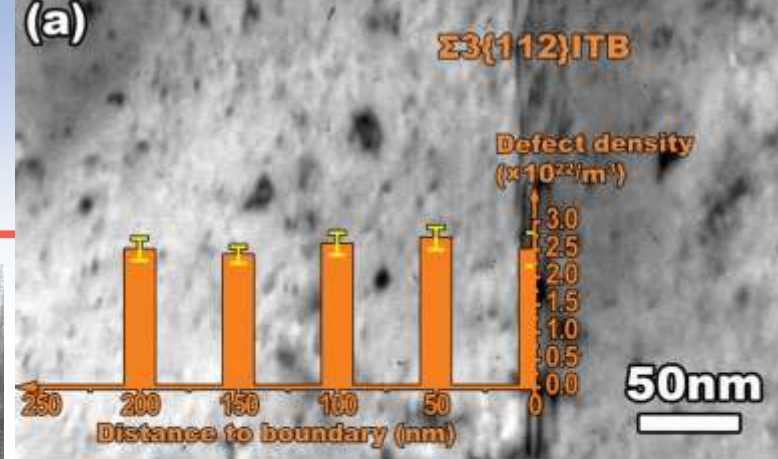
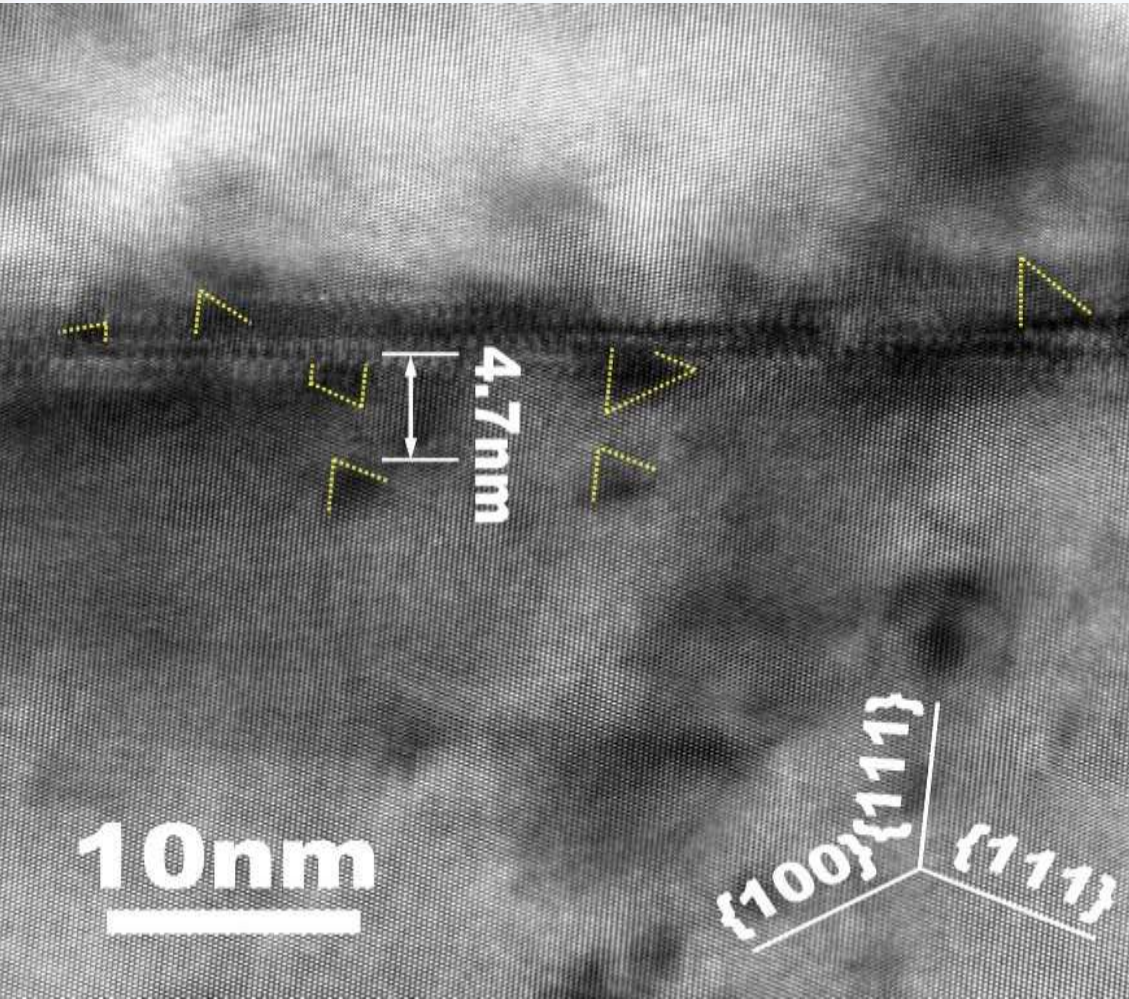
Collaborators: N. Li, A. Misra



- FIB processed sputter deposited high purity Cu foils
- Tailored to have high density of  $\Sigma 3$  boundaries

# Defect are Altered Little by the Presence of Grain Boundaries

Collaborators: N. Li, A. Misra

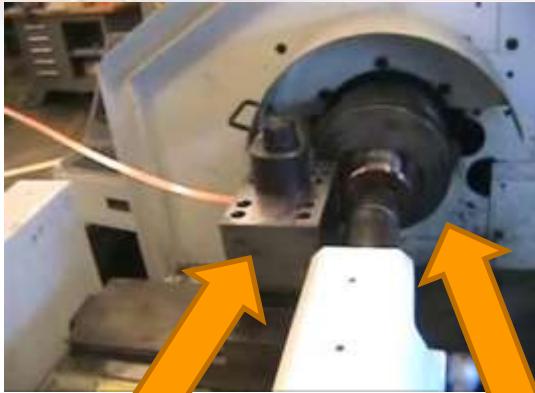


SFT appear to be directly at GB

No change in defect density is observed near GB

# What Insight into Structural Stability is Gained from I<sup>3</sup>TEM Experiments?

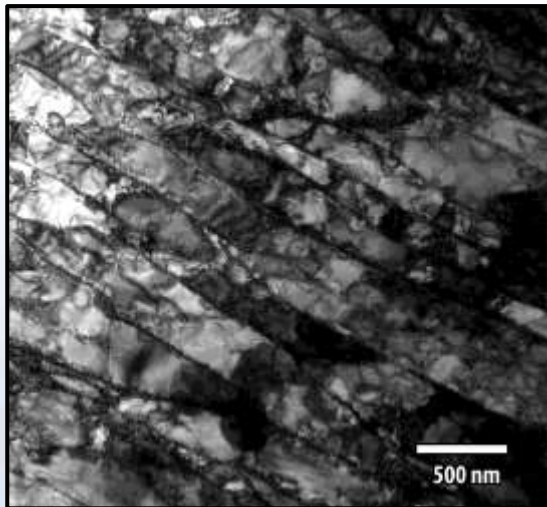
Collaborators: O. El-Atwani, D. Buller, & J.A. Scott



Extrusion  
Machining tooling

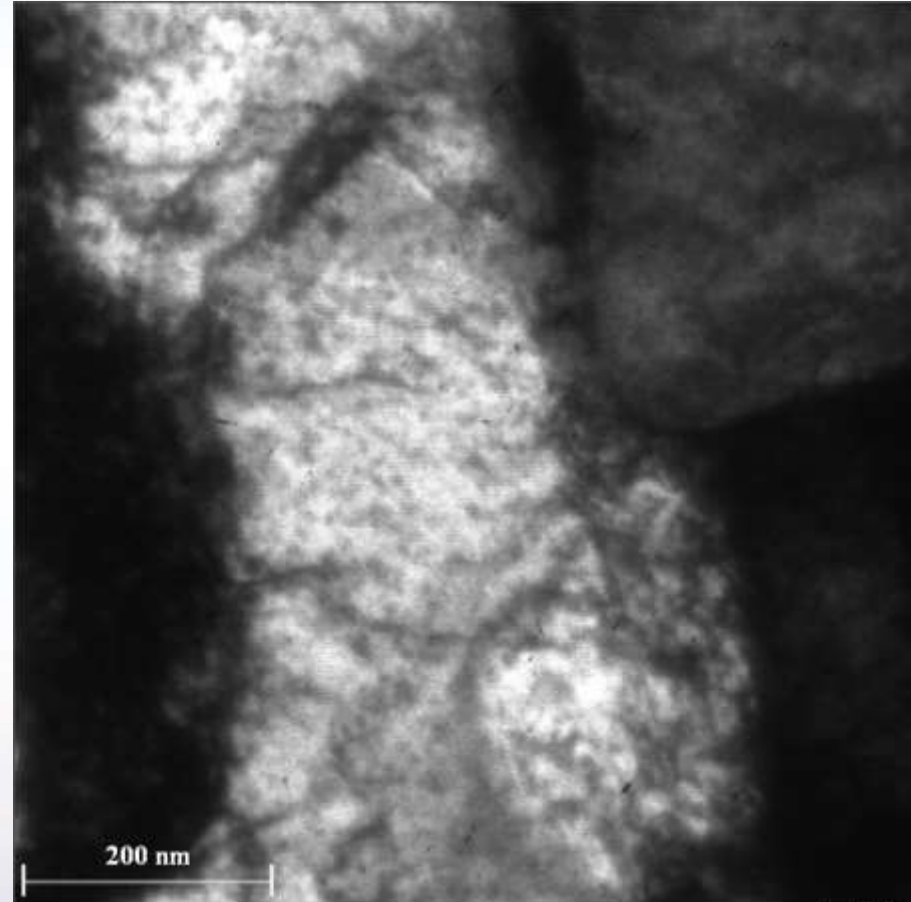
Commercially  
available lathe

From NW  
components through  
proposed NE  
cladding to waste  
storage:  
Understanding  
Radiation Damage is  
Essential



UFG Tungsten

- I<sup>3</sup>TEM W irradiation and He implantation of SPD-W developed for ITER applications



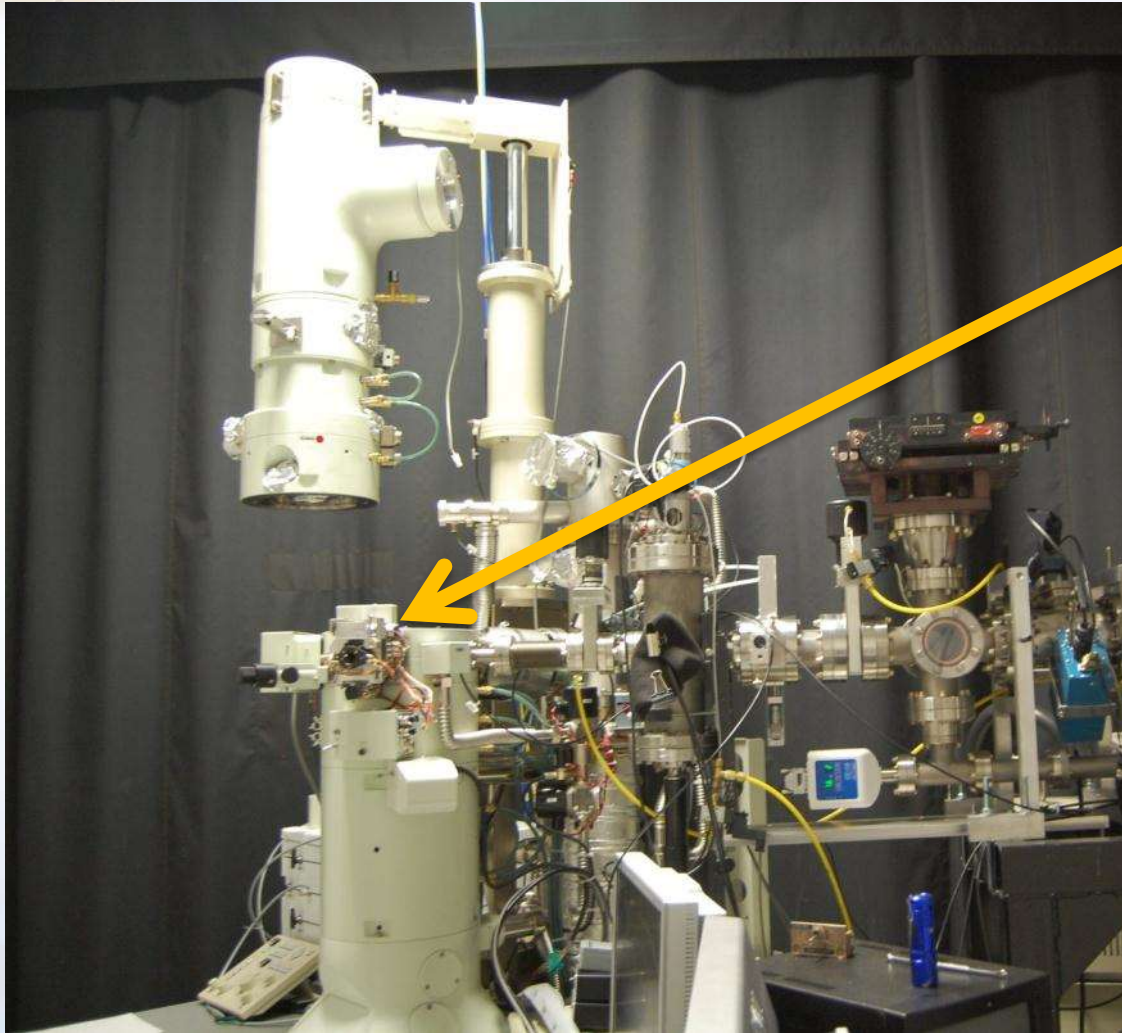
I<sup>3</sup>TEM is providing insight into:

- 1) Loop formation
- 2) Loop stability & migration
- 3) Rad & structural defect interactions

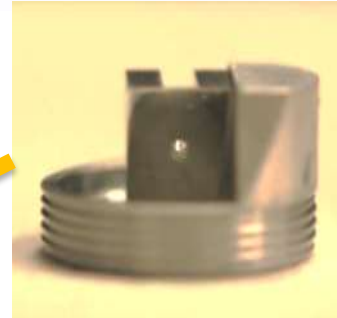




# *In situ* TEM Luminescence



Optical Mirror in TEM



First IBIL in TEM



## Optical Pathway in an I<sup>3</sup>TEM

- Angled mirror with bore hole for the electron path was installed.
- Mirror is located on top of the objective polepiece “heart of the TEM”
- Port was constructed with thick leaded glass to permit light through, but not x-rays created by ion or electron beams.
- Permits *in situ* IBIL.

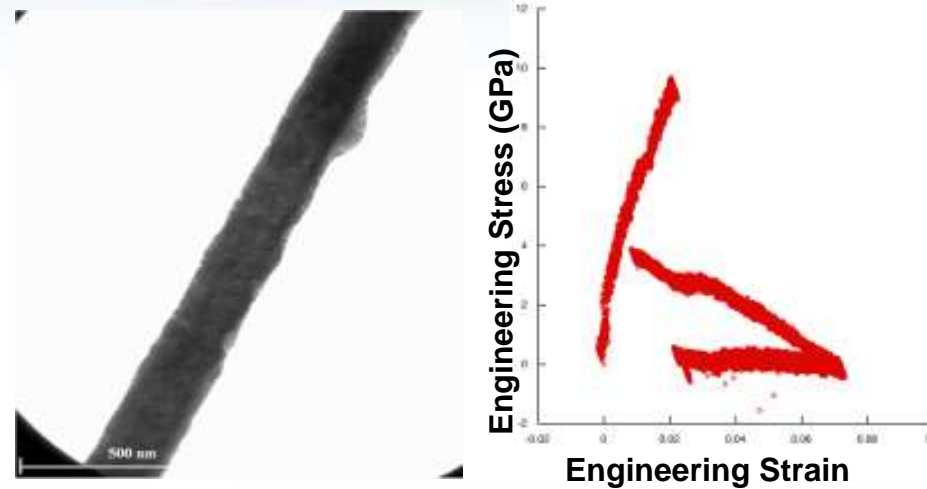
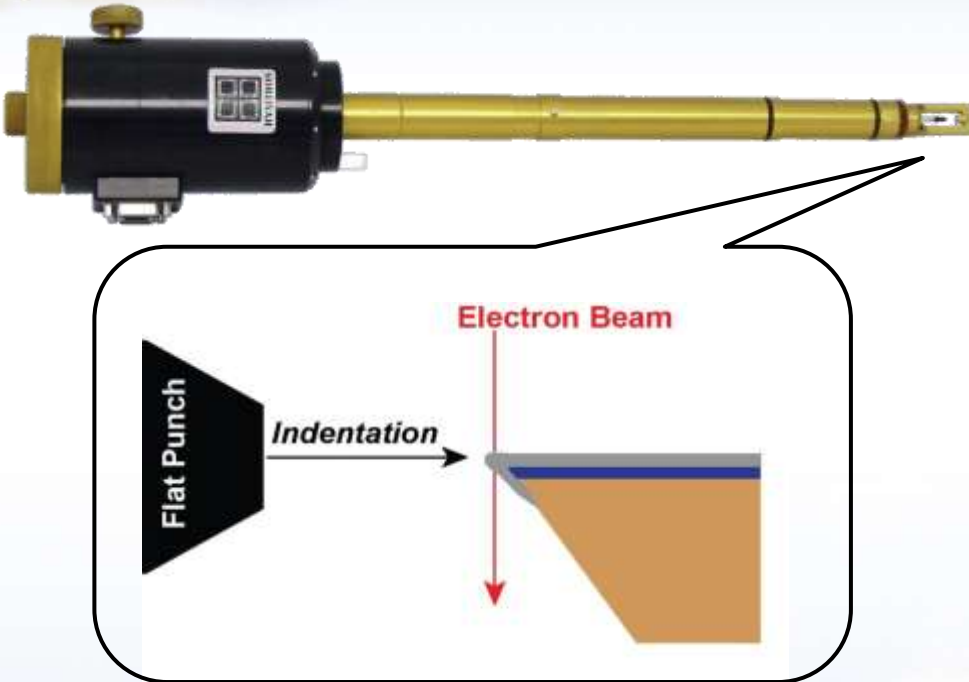
An optical port was added to the I<sup>3</sup>TEM, which permits *in situ* TEM luminescence studies



Sandia National Laboratories

# *In situ* TEM Quantitative Mechanical Testing

Contributors: J. Sharon, B. L. Boyce, C. Chisholm, H. Bei, E.P. George, P. Hosemann, A.M. Minor, & Hysitron Inc.



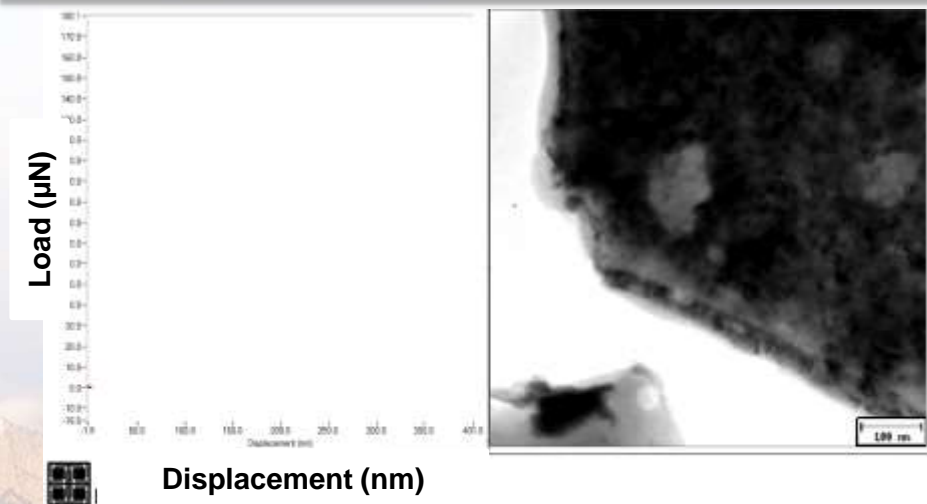
Displacement damage effect on mech. prop.

## Radiation effect on mechanical properties

- Direct correlation of dose and defect density with resulting change in strength and ductility
- Failure of Mo-wire after 3 MeV Cu irradiation

## Contact effect on structure

- Associate change in local hardness and fatigue with nanocrystalline Cu film structural evolution

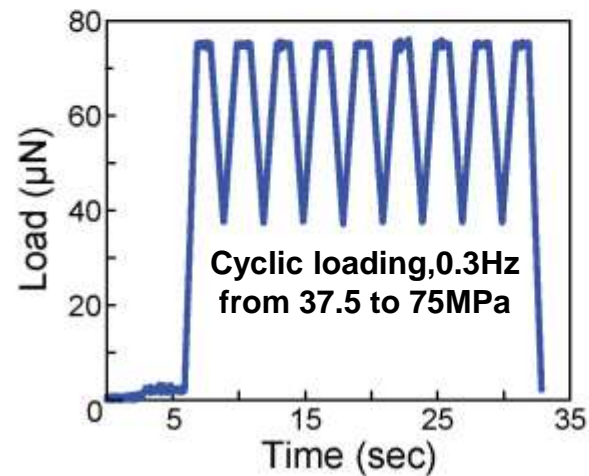
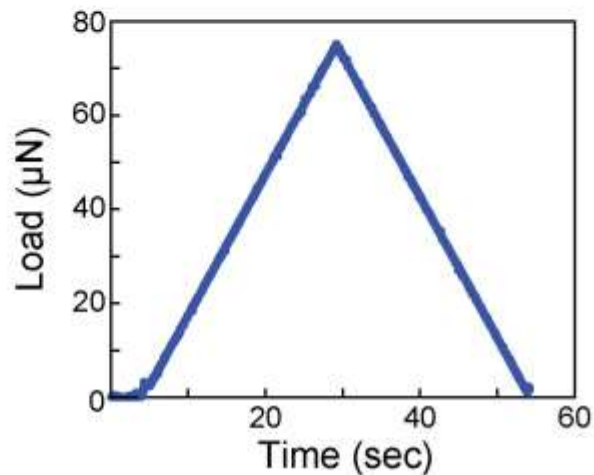
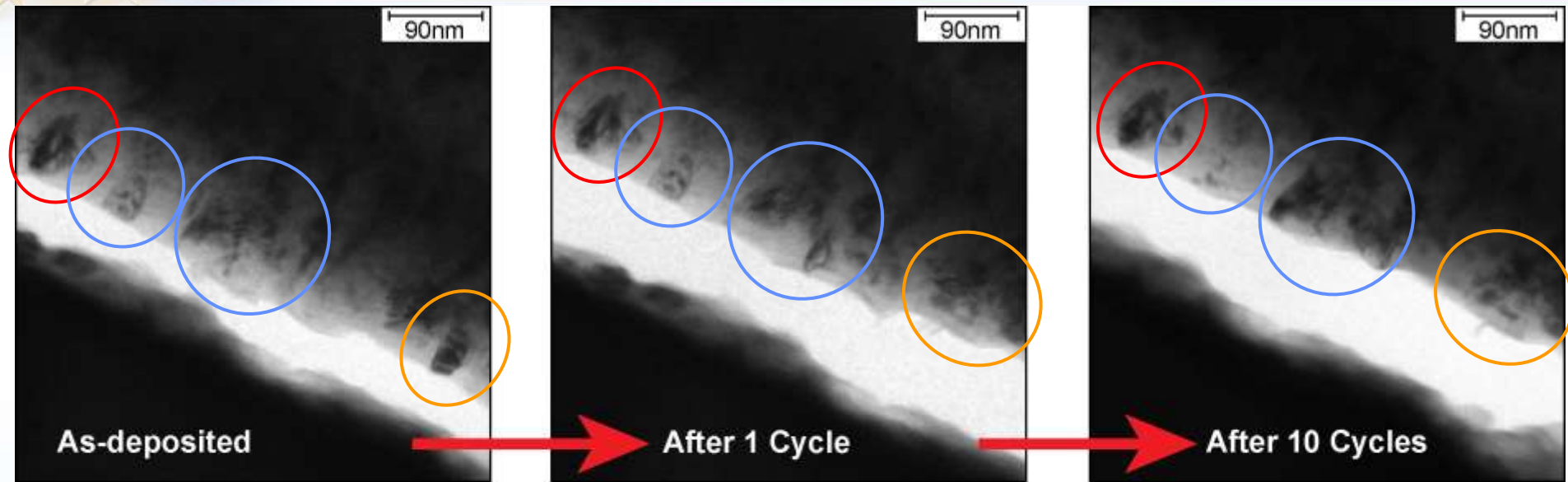


Fundamentals of contact reliability



# No, Monotonic, or Cyclic Evolution

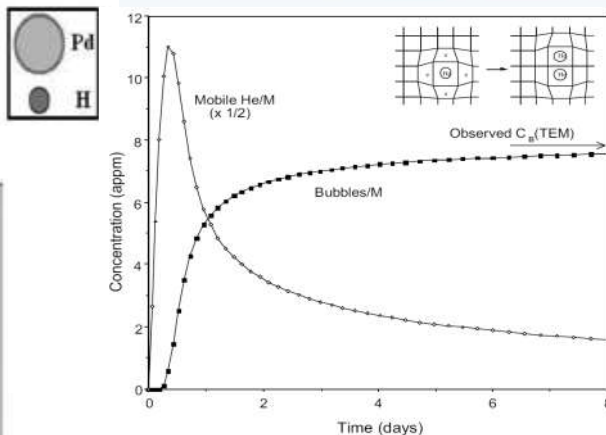
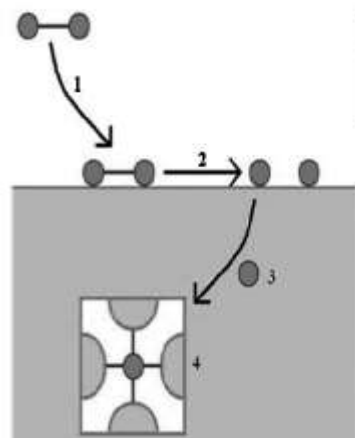
Contributors: J. Sharon, B. L. Boyce



375 MPa nominal contact stress

# Can *In situ* TEM Address Hydrogen Storage Concerns in Extreme Environments?

Contributors: B.G. Clark, P.J. Cappillino, B.W. Jacobs, M.A. Hekmaty, D.B. Robinson, L.R. Parent, I. Arslan. & Protochips, Inc.



R. Delmelle, J., Phys. Chem. Chem. Phys. (2011) p.11412

Cowgill, D., Fusion Sci. & Tech., 28 (2005) p. 539

Trinkaas, H. *et al.*, JNM (2003) p. 229

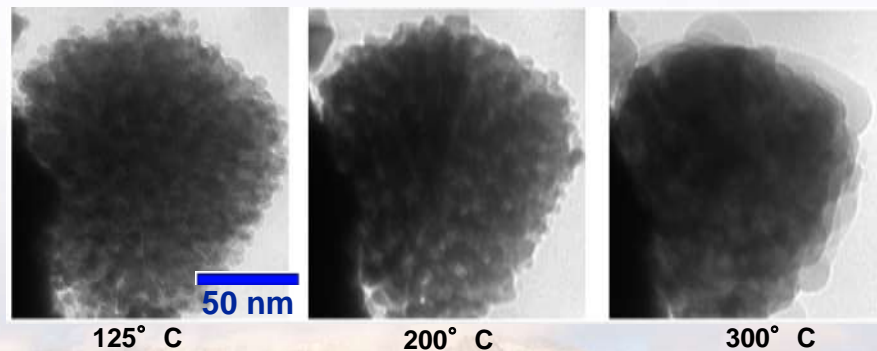
Thiebaut, S. *et al.* JNM (2000) p. 217

## Vapor-Phase Heating TEM Stage

- Compatible with a range of gases
- In situ* resistive heating
- Continuous observation of the reaction channel
- Chamber dimensions are controllable
- Compatible with MS and other analytical tools

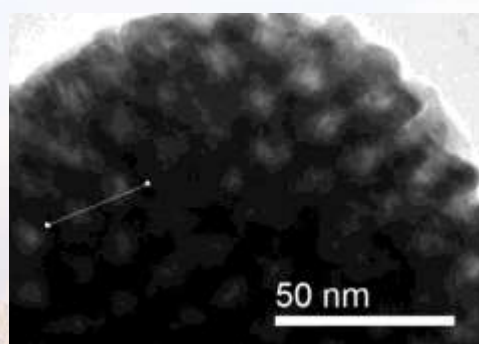
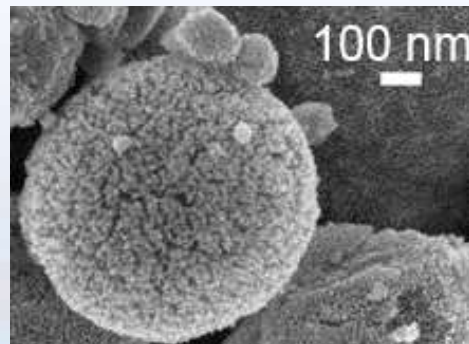


- 1 atm H<sub>2</sub> after several pulses to specified temp.



New *in situ* atmospheric heating experiments provide great insight into nanoporous Pd stability

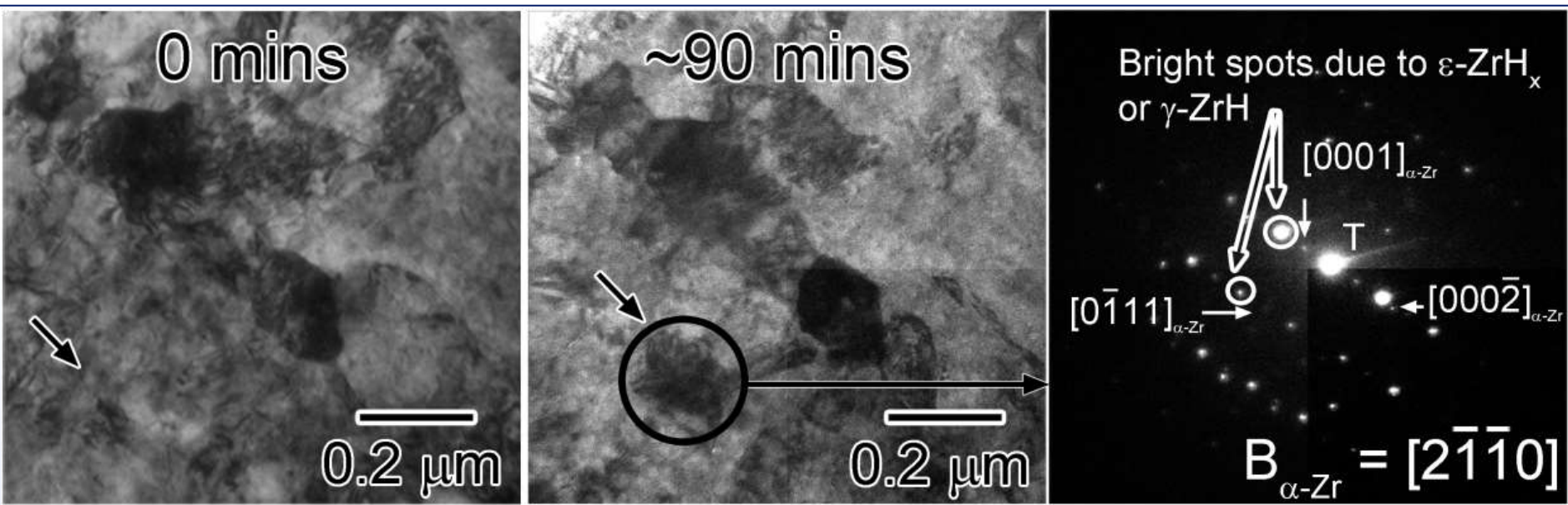
Harmful effects may be mitigated in nanoporous Pd



# In situ Observation of Hydride Formation in Zirlo

Collaborators: S. Rajasekhara and B.G. Clark

Absolute hydrogen pressure: 327 torr (~ 0.5 atm),  
Ramp rate: 1 °C/s, Final temperature: ~ 400 C, Dwell time: ~ 90 mins



Hydride formation shown, for the first time by use of a novel TEM gas-cell stage, at elevated temperature and hydrogen pressure



# Can We Gain Insight into the Corrosion Process through *In situ* TEM?

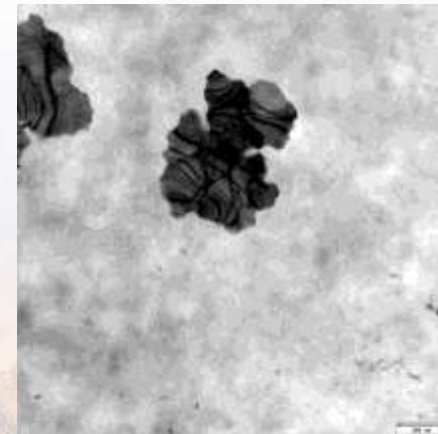
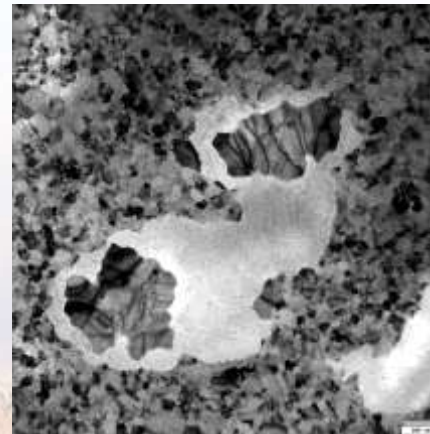
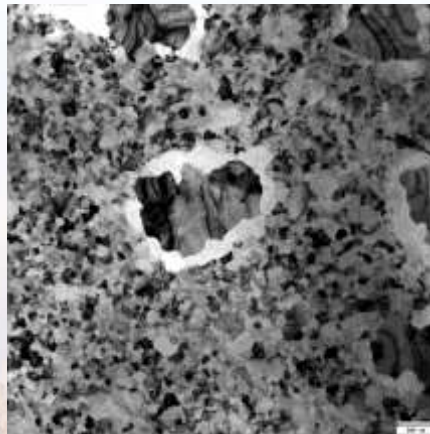
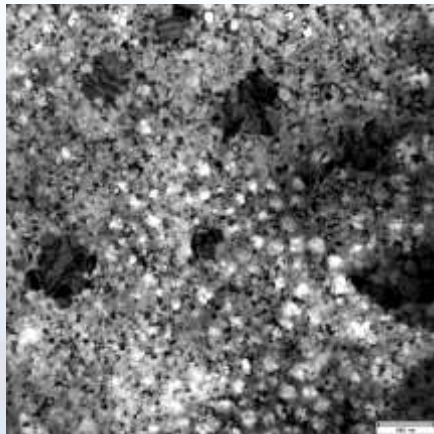
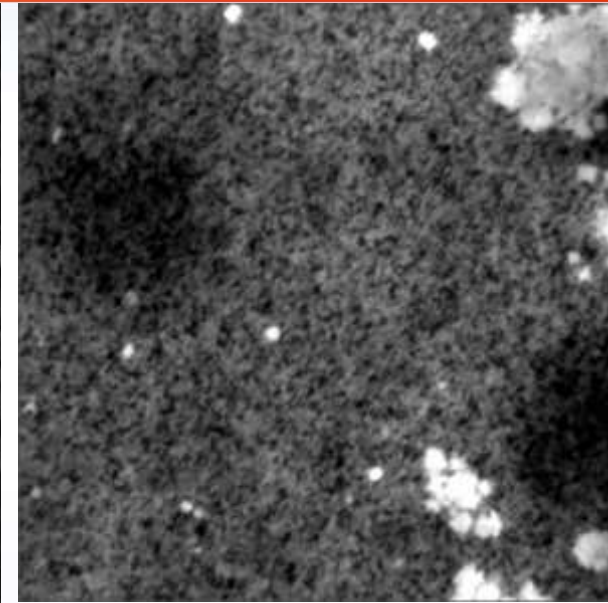
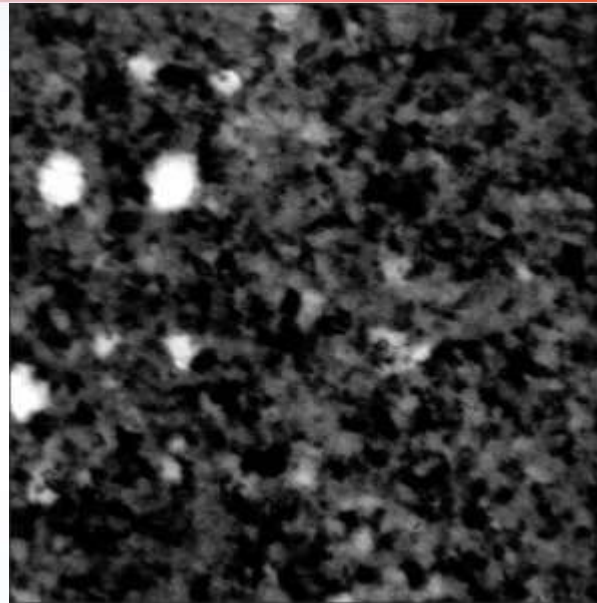
Contributors: D. Gross, J. Kacher, I.M. Robertson & Protochips, Inc.

## Microfluidic Stage

- Mixing of two or more channels
- Continuous observation of the reaction channel
- Chamber dimensions are controllable



Cross-sectional schematic



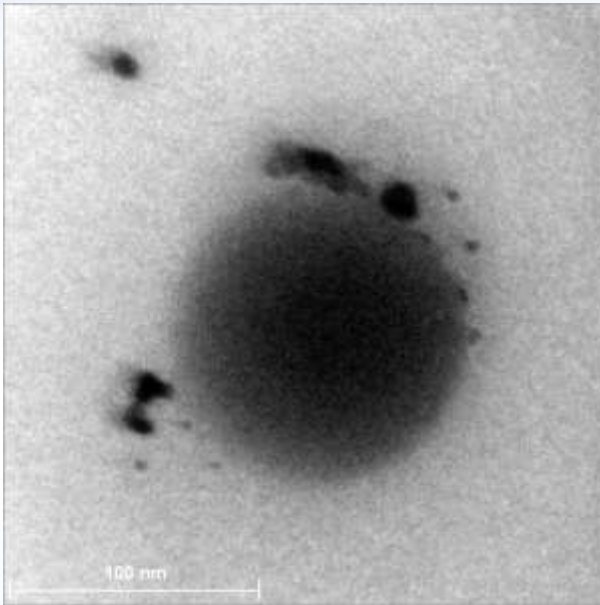
**Pitting mechanisms during dilute flow of acetic acid over 99.95% nc-PLD Fe involves many grains.  
Large grains resulting from annealing appear more corrosion tolerant**

# Other Fun Uses of Microfluidic Cell

## Protocell Drug Delivery

S. Hoppe,  
E. Carnes,  
J. Brinker

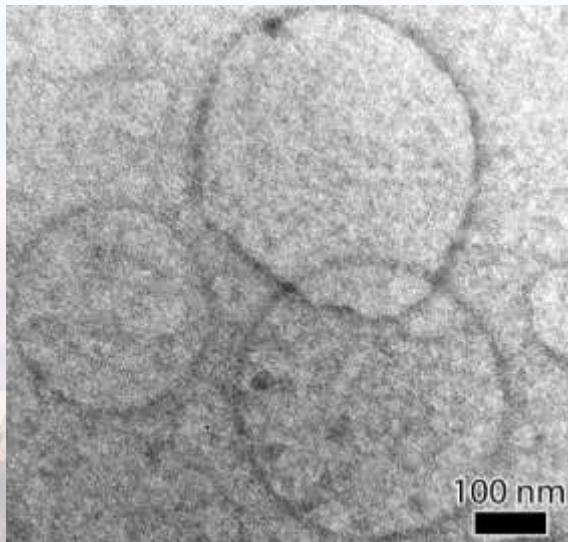
Liposome  
encapsulated  
Silica destroyed  
by the electron  
beam



## Liposomes in Water

S. Hoppe,  
D. Sasaki

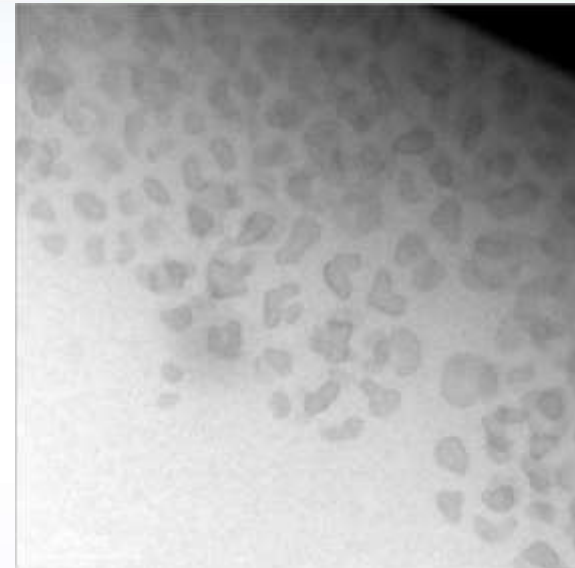
Liposomes  
imaged in  
flowing aqueous  
channel



## BSA Crystallization

S. Hoppe

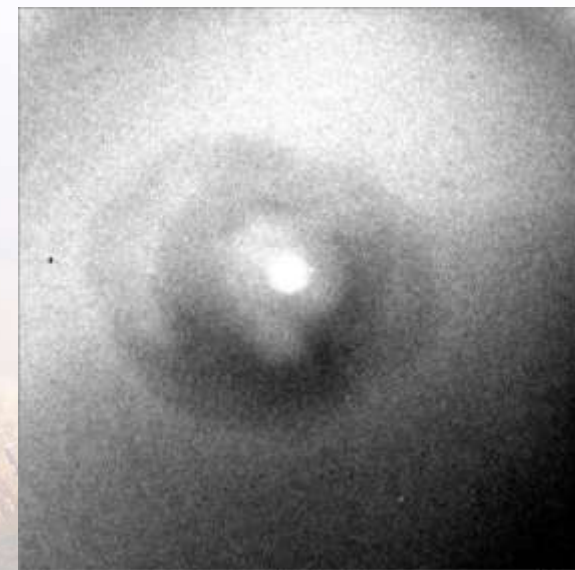
Crystallization of excess  
Bovine Serum Albumen  
during flow



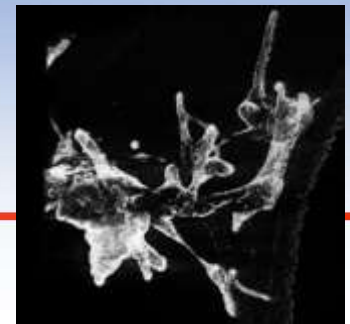
## La Structure Formation

S. Hoppe,  
T. Nenoff

La  
Nanostructure  
form from  $\text{LaCl}_3$   
 $\text{H}_2\text{O}$  in wet cell  
due to beam  
effects



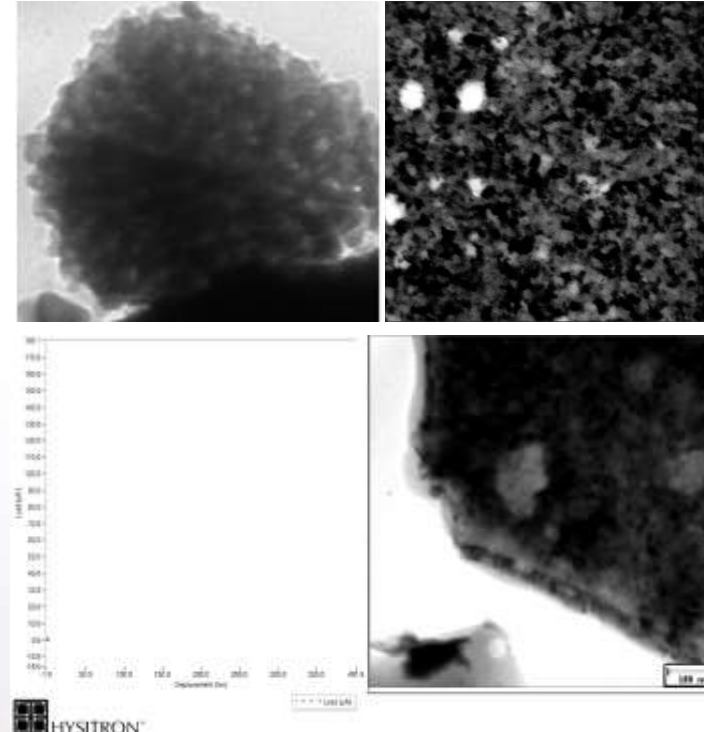
# Summary



- Sandia's I<sup>3</sup>TEM is one of only two facilities in the US
  - Only facility in the world with a wealth of dual *in situ* capabilities
  - *In situ* irradiation from H to Au
  - *In situ* gas implantation
  - Eight TEM stages with various capabilities (two beta-testing)

## Future Interests

- Apply the current I<sup>3</sup>TEM capabilities to various material systems of interest to internal and external customers
- Expand the I<sup>3</sup>TEM capability to include
  - Nano to microsecond imaging
  - Laser heating and/or shock to the sample
  - Addition of precession electron diffraction



**Sandia's I<sup>3</sup>TEM although still under development is providing a wealth of interesting initial observations**

### Contributors & Collaborators:

Paul G. Kotula, Ping Lu, Don Susan, Zahra Ghanbari, Jan Ringnald, C. Chan, J. Carroll, J. Madison, M. Rye, J. Michael, J.D. Sugar, F. El Gabaly, Chueh, J. Huang, Y. Liu, J.P. Sullivan, B.L. Doyle, O. El-Atwani, D. Buller, J.A. Scott, B.A. Hernandez-Sanchez, T.J. Boyle, J. Villone, P. Yang, J. Sharon, B. L. Boyce, C. Chisholm, H. Bei, E.P. George, P. Hosemann, A.M. Minor, Hysitron Inc., H. Lim, C. Battaile, S.M. Hoppe, D. Sasaki, Protochips, Inc., S. Rajasekhara, N.R. Sorensen, B.G. Clark, D. Gross, J. Kacher, P.J. Cappillino, B.W. Jacobs, G. Kellogg, T. Ohta, B. Diaconescu, L.R. Parent, I. Arslan, T. Beechem, M.A. Hekmaty, D.B. Robinson, J Hinks, & I.M. Robertson

